



#5
7/16/03
Moulish

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Warren M. Farnworth

Serial No.: 10/043,468

Filed: January 10, 2002

For: METHOD OF FORMING
OVERMOLDED CHIP SCALE PACKAGE
AND RESULTING PRODUCT

Confirmation No.: 7094

Examiner: K. Nguyen

Group Art Unit: 2823

Attorney Docket No.: 2269-3085.4US
(96-1033.04/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

6/16/03
Date

Doreen Neumann
Signature

Doreen Neumann
Name (Type/Print)

RECEIVED
JUN 23 2003
TECHNOLOGY CENTER 2800

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

06/20/2003 WASFAW1 00000128 10043468

01 FC:1806

180.00 0P

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a). The listed documents were cited by the Office in co-pending Application Serial No. 09/982,748, filed on October 18, 2001, and directed to a related invention.

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as

defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
US - 5,258,648	11/02/1993	Lin
US - 5,340,771	08/23/1994	Rostoker
US - 5,450,283	09/12/1995	Lin et al.
US - 5,615,477	04/01/1997	Sweitzer
US - 5,686,318	11/11/1997	Farnworth et al.
US - 5,883,438	03/16/1999	Kang
US - 5,998,242	12/07/1999	Kirkpatrick et al.
US - 6,048,753	04/11/2000	Farnworth et al.
US - 6,060,891	05/09/2000	Hembree et al.
US - 6,144,101	11/07/2000	Akram

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits. The fee pursuant to 37 C.F.R. § 1.17(p) is enclosed.

Respectfully submitted,



Edgar R. Cataxinos
Registration No. 39,931
Attorney for Applicant(s)
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: June 16, 2003

ERC/ps:dn

Enclosures: Form PTO/SB/08

Copy of documents cited

Check No. 4515 in the amount of \$180.00

Document in ProLaw